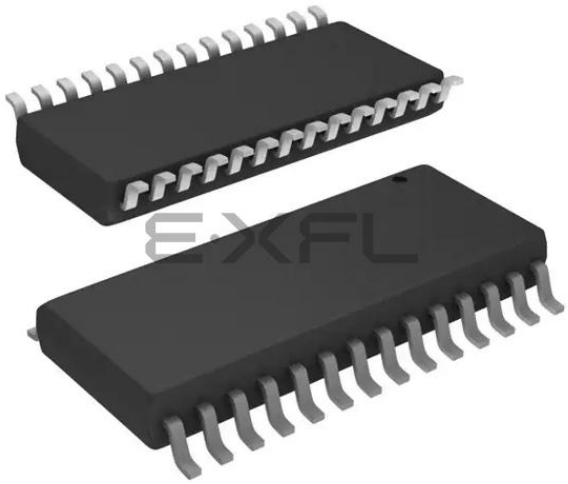

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512mc202-i-so

TABLE 2: dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X MOTOR CONTROL FAMILIES (CONTINUED)

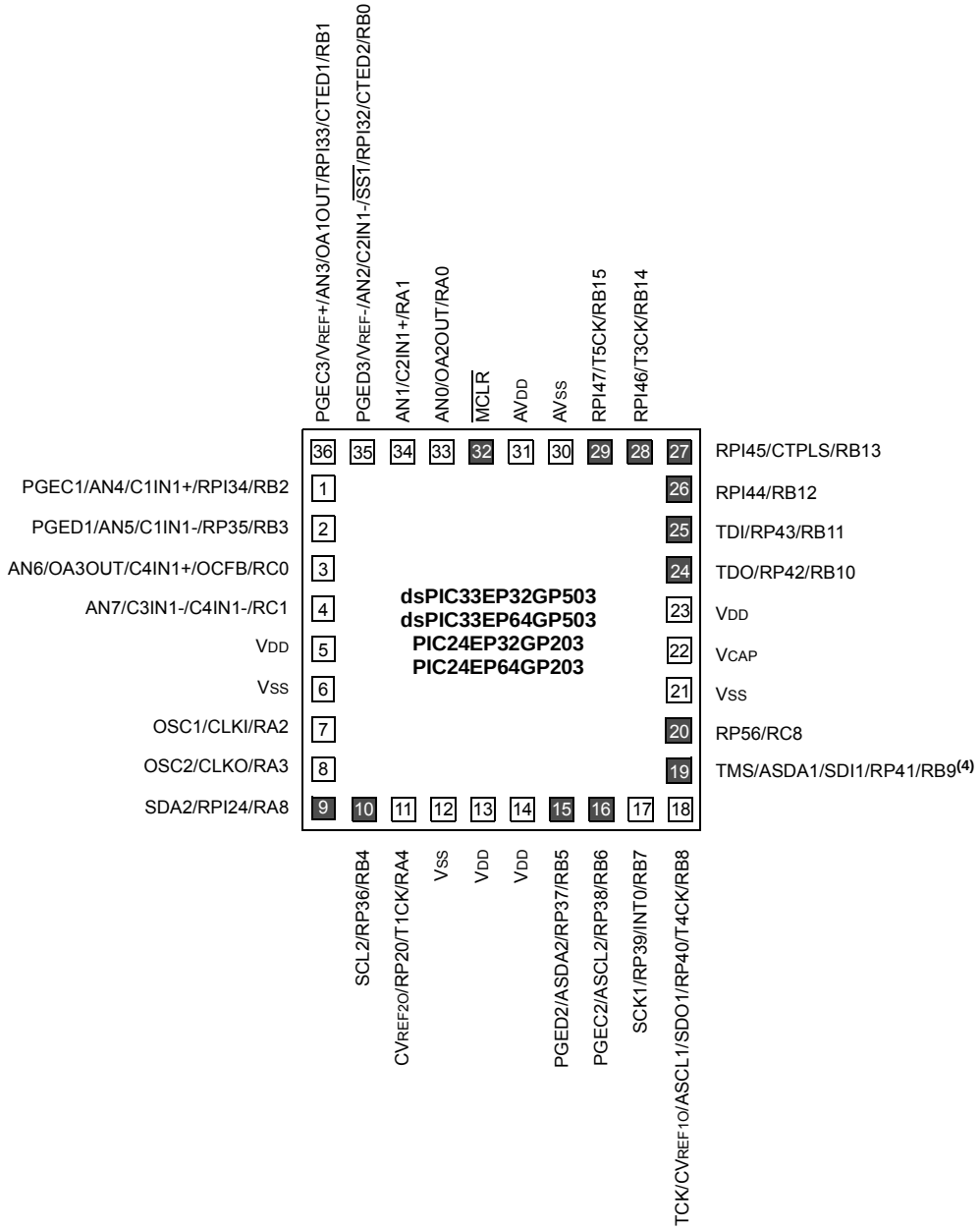
Device	Page Erase Size (Instructions)	Program Flash Memory (Kbytes)	RAM (Kbytes)	Remappable Peripherals									I^2C™	CRC Generator	10-Bit/12-Bit ADC (Channels)	Op Amps/Comparators	CTMU	PTG	I/O Pins	Pins	Packages
				16-Bit/32-Bit Timers	Input Capture	Output Compare	Motor Control PWM(4) (Channels)	Quadrature Encoder Interface	UART	SPI(2)	ECAN™ Technology	External Interrupts(3)									
dsPIC33EP32MC504	512	32	4	5	4	4	6	1	2	2	1	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(5), TQFP, QFN, UQFN
dsPIC33EP64MC504	1024	64	8																		
dsPIC33EP128MC504	1024	128	16																		
dsPIC33EP256MC504	1024	256	32																		
dsPIC33EP512MC504	1024	512	48																		
dsPIC33EP64MC506	1024	64	8	5	4	4	6	1	2	2	1	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
dsPIC33EP128MC506	1024	128	16																		
dsPIC33EP256MC506	1024	256	32																		
dsPIC33EP512MC506	1024	512	48																		

Note 1: On 28-pin devices, Comparator 4 does not have external connections. Refer to **Section 25.0 "Op Amp/Comparator Module"** for details.
2: Only SPI2 is remappable.
3: INT0 is not remappable.
4: Only the PWM Faults are remappable.
5: The SSOP and VTLA packages are not available for devices with 512 Kbytes of memory.

Pin Diagrams (Continued)

36-Pin VTLA(1,2,3)

■ = Pins are up to 5V tolerant



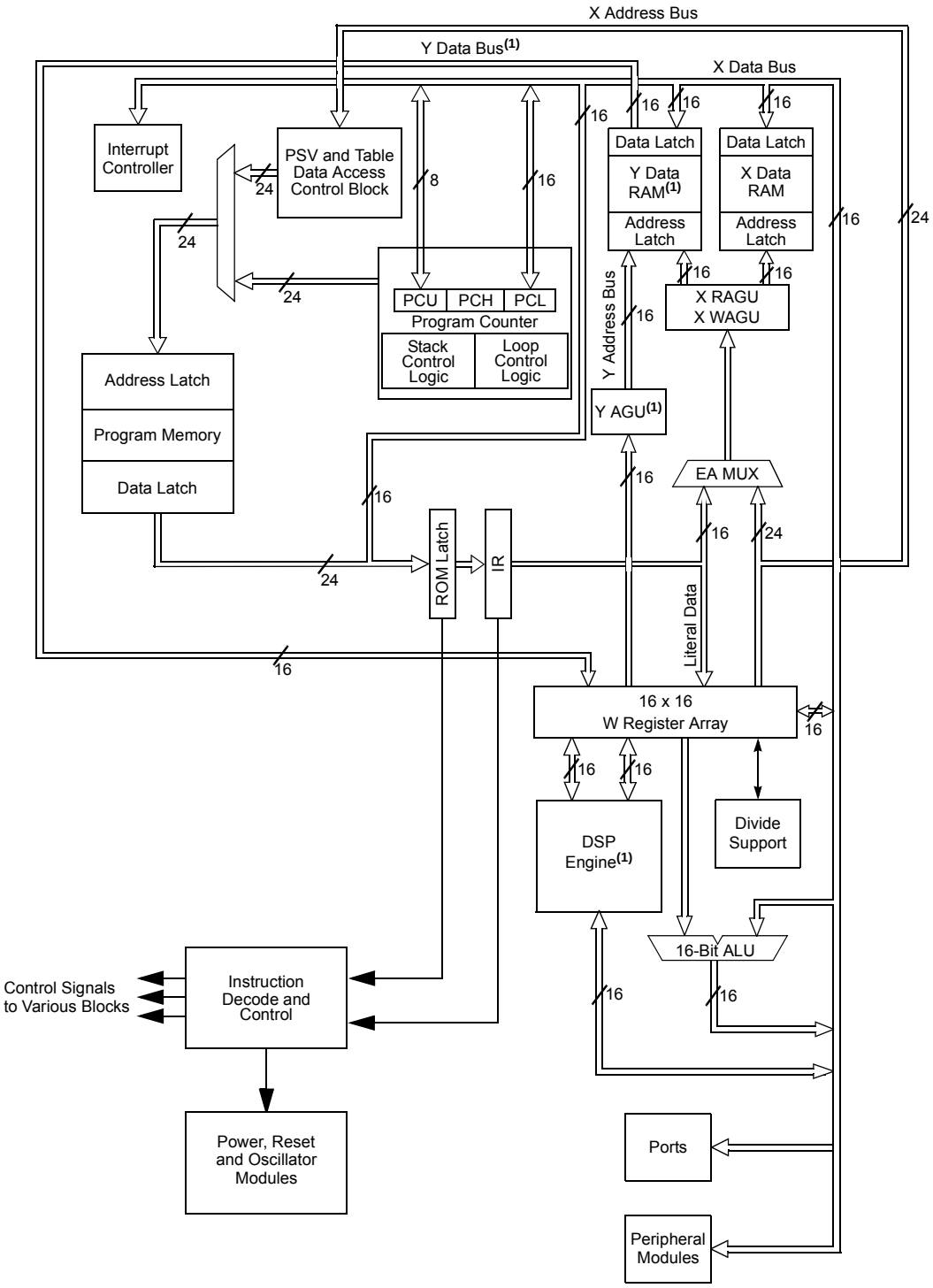
Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

FIGURE 3-1: dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X CPU BLOCK DIAGRAM



Note 1: This feature is not available on PIC24EPXXXGP/MC20X devices.

REGISTER 7-7: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
VECNUM7	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7-0 **VECNUM<7:0>:** Vector Number of Pending Interrupt bits
11111111 = 255, Reserved; do not use
•
•
•
00001001 = 9, IC1 – Input Capture 1
00001000 = 8, INT0 – External Interrupt 0
00000111 = 7, Reserved; do not use
00000110 = 6, Generic soft error trap
00000101 = 5, DMAC error trap
00000100 = 4, Math error trap
00000011 = 3, Stack error trap
00000010 = 2, Generic hard trap
00000001 = 1, Address error trap
00000000 = 0, Oscillator fail trap

REGISTER 9-3: PLLFBD: PLL FEEDBACK DIVISOR REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	PLLDIV8
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-0
PLLDIV7	PLLDIV6	PLLDIV5	PLLDIV4	PLLDIV3	PLLDIV2	PLLDIV1	PLLDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8-0 **PLLDIV<8:0>:** PLL Feedback Divisor bits (also denoted as ‘M’, PLL multiplier)

111111111 = 513
•
•
•
000110000 = 50 (default)
•
•
•
000000010 = 4
000000001 = 3
000000000 = 2

11.5 I/O Helpful Tips

1. In some cases, certain pins, as defined in Table 30-11, under “Injection Current”, have internal protection diodes to VDD and VSS. The term, “Injection Current”, is also referred to as “Clamp Current”. On designated pins, with sufficient external current-limiting precautions by the user, I/O pin input voltages are allowed to be greater or less than the data sheet absolute maximum ratings, with respect to the VSS and VDD supplies. Note that when the user application forward biases either of the high or low side internal input clamp diodes, that the resulting current being injected into the device, that is clamped internally by the VDD and VSS power rails, may affect the ADC accuracy by four to six counts.
2. I/O pins that are shared with any analog input pin (i.e., ANx) are always analog pins by default after any Reset. Consequently, configuring a pin as an analog input pin automatically disables the digital input pin buffer and any attempt to read the digital input level by reading PORTx or LATx will always return a ‘0’, regardless of the digital logic level on the pin. To use a pin as a digital I/O pin on a shared ANx pin, the user application needs to configure the Analog Pin Configuration registers in the I/O ports module (i.e., ANSELx) by setting the appropriate bit that corresponds to that I/O port pin to a ‘0’.

Note:	Although it is not possible to use a digital input pin when its analog function is enabled, it is possible to use the digital I/O output function, TRISx = 0x0, while the analog function is also enabled. However, this is not recommended, particularly if the analog input is connected to an external analog voltage source, which would create signal contention between the analog signal and the output pin driver.

3. Most I/O pins have multiple functions. Referring to the device pin diagrams in this data sheet, the priorities of the functions allocated to any pins are indicated by reading the pin name from left-to-right. The left most function name takes precedence over any function to its right in the naming convention. For example: AN16/T2CK/T7CK/RC1. This indicates that AN16 is the highest priority in this example and will supersede all other functions to its right in the list. Those other functions to its right, even if enabled, would not work as long as any other function to its left was enabled. This rule applies to all of the functions listed for a given pin.
4. Each pin has an internal weak pull-up resistor and pull-down resistor that can be configured using the CNPUx and CNPDx registers, respectively. These resistors eliminate the need for external resistors in certain applications. The internal pull-up is up to ~(VDD – 0.8), not VDD. This value is still above the minimum VIH of CMOS and TTL devices.
5. When driving LEDs directly, the I/O pin can source or sink more current than what is specified in the VOH/IOH and VOL/IOL DC characteristic specification. The respective IOH and IOL current rating only applies to maintaining the corresponding output at or above the VOH, and at or below the VOL levels. However, for LEDs, unlike digital inputs of an externally connected device, they are not governed by the same minimum VIH/VIL levels. An I/O pin output can safely sink or source any current less than that listed in the absolute maximum rating section of this data sheet. For example:

   VOH = 2.4V @ IOH = -8 mA and VDD = 3.3V

   The maximum output current sourced by any 8 mA I/O pin = 12 mA.

   LED source current < 12 mA is technically permitted. Refer to the VOH/IOH graphs in **Section 30.0 “Electrical Characteristics”** for additional information.
6. The Peripheral Pin Select (PPS) pin mapping rules are as follows:
   a) Only one “output” function can be active on a given pin at any time, regardless if it is a dedicated or remappable function (one pin, one output).
   b) It is possible to assign a “remappable output” function to multiple pins and externally short or tie them together for increased current drive.
   c) If any “dedicated output” function is enabled on a pin, it will take precedence over any remappable “output” function.
   d) If any “dedicated digital” (input or output) function is enabled on a pin, any number of “input” remappable functions can be mapped to the same pin.
   e) If any “dedicated analog” function(s) are enabled on a given pin, “digital input(s)” of any kind will all be disabled, although a single “digital output”, at the user’s cautionary discretion, can be enabled and active as long as there is no signal contention with an external analog input signal. For example, it is possible for the ADC to convert the digital output logic level, or to toggle a digital output on a comparator or ADC input provided there is no external analog input, such as for a built-in self-test.
   f) Any number of “input” remappable functions can be mapped to the same pin(s) at the same time, including to any pin with a single output from either a dedicated or remappable “output”.

REGISTER 21-2: CxCTRL2: ECANx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT4	DNCNT3	DNCNT2	DNCNT1	DNCNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits

10010-11111 = Invalid selection
10001 = Compares up to Data Byte 3, bit 6 with EID<17>
•
•
•
00001 = Compares up to Data Byte 1, bit 7 with EID<0>
00000 = Does not compare data bytes

REGISTER 21-3: CxVEC: ECANx INTERRUPT CODE REGISTER

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0
bit 15							bit 8

U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
—	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **FILHIT<4:0>:** Filter Hit Number bits

10000-11111 = Reserved
01111 = Filter 15
•
•
•
00001 = Filter 1
00000 = Filter 0

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **ICODE<6:0>:** Interrupt Flag Code bits

1000101-1111111 = Reserved
1000100 = FIFO almost full interrupt
1000011 = Receiver overflow interrupt
1000010 = Wake-up interrupt
1000001 = Error interrupt
1000000 = No interrupt
•
•
•
0010000-0111111 = Reserved
0001111 = RB15 buffer interrupt
•
•
•
0001001 = RB9 buffer interrupt
0001000 = RB8 buffer interrupt
0000111 = TRB7 buffer interrupt
0000110 = TRB6 buffer interrupt
0000101 = TRB5 buffer interrupt
0000100 = TRB4 buffer interrupt
0000011 = TRB3 buffer interrupt
0000010 = TRB2 buffer interrupt
0000001 = TRB1 buffer interrupt
0000000 = TRB0 buffer interrupt

REGISTER 23-6: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER (CONTINUED)

bit 4-0 **CH0SA<4:0>:** Channel 0 Positive Input Select for Sample MUXA bits(1)

11111 = Open; use this selection with CTMU capacitive and time measurement
11110 = Channel 0 positive input is connected to the CTMU temperature measurement diode (CTMU TEMP)
11101 = Reserved
11100 = Reserved
11011 = Reserved
11010 = Channel 0 positive input is the output of OA3/AN6(2,3)
11001 = Channel 0 positive input is the output of OA2/AN0(2)
11000 = Channel 0 positive input is the output of OA1/AN3(2)
10110 = Reserved
•
•
•
10000 = Reserved
01111 = Channel 0 positive input is AN15(1,3)
01110 = Channel 0 positive input is AN14(1,3)
01101 = Channel 0 positive input is AN13(1,3)
•
•
•
00010 = Channel 0 positive input is AN2(1,3)
00001 = Channel 0 positive input is AN1(1,3)
00000 = Channel 0 positive input is AN0(1,3)

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

3: See the **"Pin Diagrams"** section for the available analog channels for each device.

REGISTER 23-7: AD1CSSH: ADC1 INPUT SCAN SELECT REGISTER HIGH(1)

R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	—	—	—	CSS26(2)	CSS25(2)	CSS24(2)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADC1 Input Scan Selection bit
1 = Selects CTMU capacitive and time measurement for input scan (Open)
0 = Skips CTMU capacitive and time measurement for input scan (Open)

bit 14 **CSS30:** ADC1 Input Scan Selection bit
1 = Selects CTMU on-chip temperature measurement for input scan (CTMU TEMP)
0 = Skips CTMU on-chip temperature measurement for input scan (CTMU TEMP)

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **CSS26:** ADC1 Input Scan Selection bit(2)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADC1 Input Scan Selection bit(2)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADC1 Input Scan Selection bit(2)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-0 **Unimplemented:** Read as '0'

Note 1: All AD1CSSH bits can be selected by user software. However, inputs selected for scan, without a corresponding input on the device, convert VREFL.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

NOTES:

REGISTER 25-2: CMxCON: COMPARATOR x CONTROL REGISTER (x = 1, 2 OR 3)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
CON	COE(2)	CPOL	—	—	OPMODE	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator Enable bit
1 = Op amp/comparator is enabled
0 = Op amp/comparator is disabled

bit 14 **COE:** Comparator Output Enable bit(2)
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **OPMODE:** Op Amp/Comparator Operation Mode Select bit
1 = Circuit operates as an op amp
0 = Circuit operates as a comparator

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to the EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = $V_{IN+} > V_{IN-}$
0 = $V_{IN+} < V_{IN-}$
When CPOL = 1 (inverted polarity):
1 = $V_{IN+} < V_{IN-}$
0 = $V_{IN+} > V_{IN-}$

Note 1: Inputs that are selected and not available will be tied to V_{SS}. See the **"Pin Diagrams"** section for available inputs for each package.

2: This output is not available when OPMODE (CMxCON<10>) = 1.

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER (CONTINUED)

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Reference Select bit (VIN+ input)(1)
1 = VIN+ input connects to internal CVREFIN voltage
0 = VIN+ input connects to C4IN1+ pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Channel Select bits(1)
11 = VIN- input of comparator connects to OA3/AN6
10 = VIN- input of comparator connects to OA2/AN0
01 = VIN- input of comparator connects to OA1/AN3
00 = VIN- input of comparator connects to C4IN1-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

REGISTER 25-6: CMxFLTR: COMPARATOR x FILTER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	CFSEL2	CFSEL1	CFSEL0	CFLTREN	CFDIV2	CFDIV1	CFDIV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **CFSEL<2:0>:** Comparator Filter Input Clock Select bits
111 = T5CLK(1)
110 = T4CLK(2)
101 = T3CLK(1)
100 = T2CLK(2)
011 = Reserved
010 = SYNCO1(3)
001 = FOSC(4)
000 = FP(4)

bit 3 **CFLTREN:** Comparator Filter Enable bit
1 = Digital filter is enabled
0 = Digital filter is disabled

bit 2-0 **CFDIV<2:0>:** Comparator Filter Clock Divide Select bits
111 = Clock Divide 1:128
110 = Clock Divide 1:64
101 = Clock Divide 1:32
100 = Clock Divide 1:16
011 = Clock Divide 1:8
010 = Clock Divide 1:4
001 = Clock Divide 1:2
000 = Clock Divide 1:1

Note 1: See the Type C Timer Block Diagram (Figure 13-2).
2: See the Type B Timer Block Diagram (Figure 13-1).
3: See the High-Speed PWMx Module Register Interconnection Diagram (Figure 16-2).
4: See the Oscillator System Diagram (Figure 9-1).

TABLE 27-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
GCP	General Segment Code-Protect bit 1 = User program memory is not code-protected 0 = Code protection is enabled for the entire program memory space
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Start up device with FRC, then automatically switch to the user-selected oscillator source when ready 0 = Start up device with user-selected oscillator source
PWMLOCK(1)	PWM Lock Enable bit 1 = Certain PWM registers may only be written after a key sequence 0 = PWM registers may be written without a key sequence
FNOSC<2:0>	Oscillator Selection bits 111 = Fast RC Oscillator with Divide-by-N (FRCDIVN) 110 = Fast RC Oscillator with Divide-by-16 (FRCDIV16) 101 = Low-Power RC Oscillator (LPRC) 100 = Reserved; do not use 011 = Primary Oscillator with PLL module (XT + PLL, HS + PLL, EC + PLL) 010 = Primary Oscillator (XT, HS, EC) 001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCPLL) 000 = Fast RC Oscillator (FRC)
FCKSM<1:0>	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	Peripheral Pin Select Configuration bit 1 = Allow only one reconfiguration 0 = Allow multiple reconfigurations
OSCIOFNC	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is the clock output 0 = OSC2 is a general purpose digital I/O pin
POSCMD<1:0>	Primary Oscillator Mode Select bits 11 = Primary Oscillator is disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	Watchdog Timer Enable bit 1 = Watchdog Timer is always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer is enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
PLLKEN	PLL Lock Enable bit 1 = PLL lock is enabled 0 = PLL lock is disabled

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

TABLE 30-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	8	—	μA	-40°C	3.3V
DC61a	10	—	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 30-10: DC CHARACTERISTICS: DOZE CURRENT (I_{DOZE})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	**Typ.**	**Max.**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (I_{DOZE})(1)							
DC73a(2)	35	—	1:2	mA	-40°C	3.3V	FOSC = 140 MHz
DC73g	20	30	1:128	mA			
DC70a(2)	35	—	1:2	mA	+25°C	3.3V	FOSC = 140 MHz
DC70g	20	30	1:128	mA			
DC71a(2)	35	—	1:2	mA	+85°C	3.3V	FOSC = 140 MHz
DC71g	20	30	1:128	mA			
DC72a(2)	28	—	1:2	mA	+125°C	3.3V	FOSC = 120 MHz
DC72g	15	30	1:128	mA			

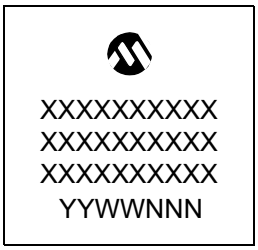
Note 1: I_{DOZE} is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all I_{DOZE} measurements are as follows:

- Oscillator is configured in EC mode and external clock is active, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (all PMDx bits are zeroed)
- CPU is executing `while(1)` statement
- JTAG is disabled

2: Parameter is characterized but not tested in manufacturing.

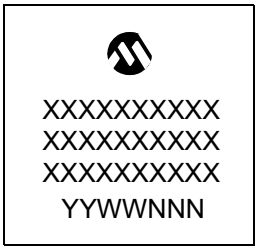
33.1 Package Marking Information (Continued)

36-Lead VTLA (TLA)



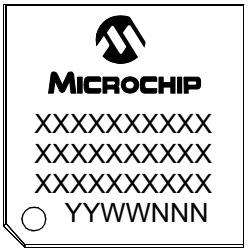
Example

44-Lead VTLA (TLA)



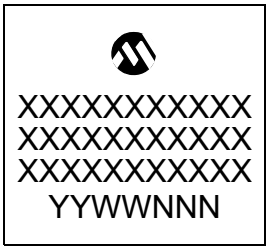
Example

44-Lead TQFP



Example

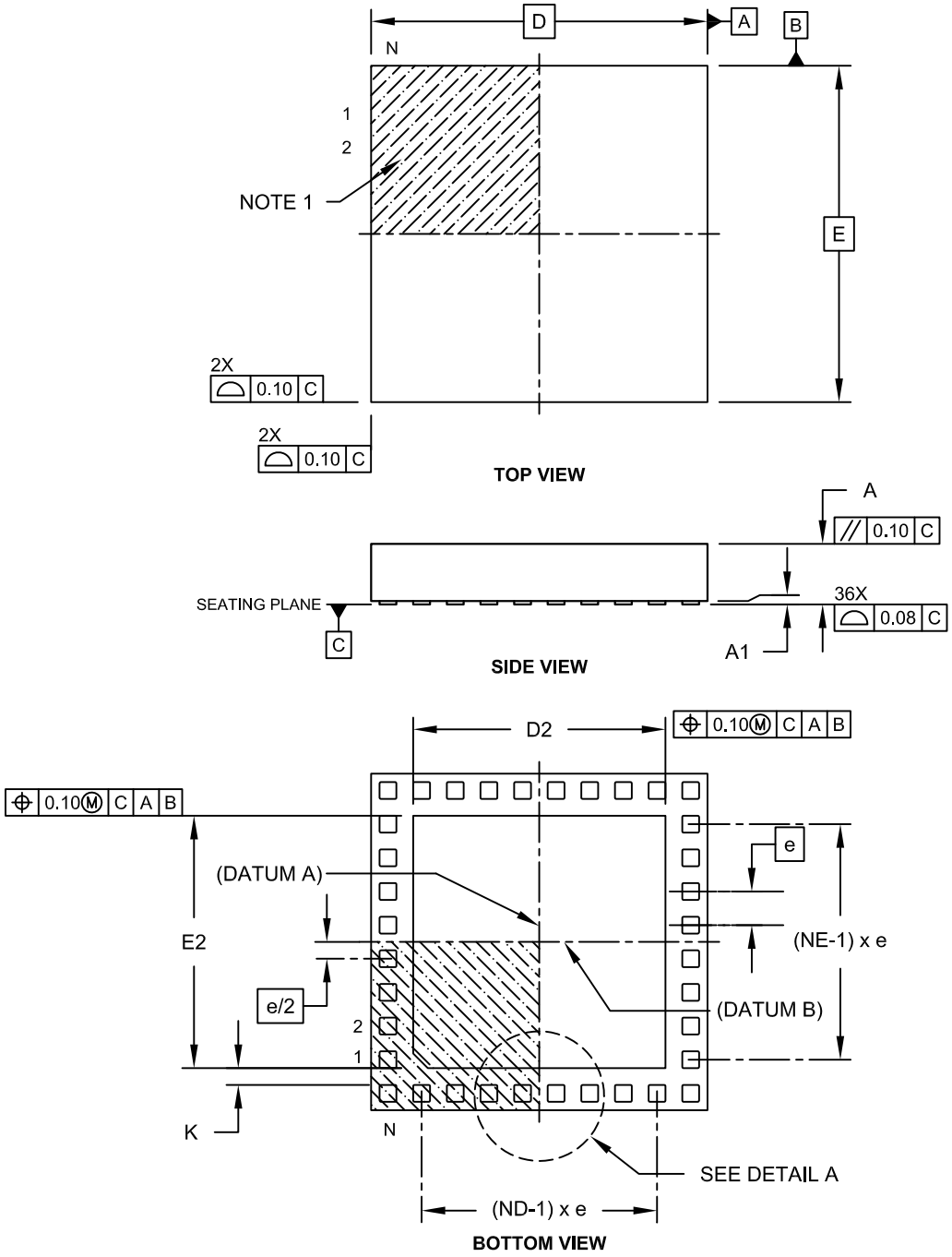
44-Lead QFN (8x8x0.9 mm)



Example

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-187C Sheet 1 of 2

Revision D (December 2011)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-3.

TABLE A-3: MAJOR SECTION UPDATES

Section Name	Update Description
"16-bit Microcontrollers and Digital Signal Controllers (up to 512-Kbyte Flash and 48-Kbyte SRAM) with High-Speed PWM, Op amps, and Advanced Analog"	Removed the Analog Comparators column and updated the Op amps/Comparators column in Table 1 and Table 2.
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 30.0 "Electrical Characteristics"	Updated the V_{BOR} specifications and/or its related note in the following electrical characteristics tables: • Table 30-1 • Table 30-4 • Table 30-12 • Table 30-14 • Table 30-15 • Table 30-16 • Table 30-56 • Table 30-57 • Table 30-58 • Table 30-59 • Table 30-60

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

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Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.